



free  
halogen®

FOR ASIA  
DSP 618D  
(Sn/Ag/Cu)  
LEAD FREE  
NO CLEAN SOLDER  
PASTE

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## Physical Properties

### Solder Composition

Qualitek Sn/Ag/Cu (Tin/Silver/Cu) Alloys are designed as a lead-free alternative for Sn/Pb alloys for electronics assembly operations. The Qualitek Sn/Ag/Cu alloys conform and exceed the impurity requirements of J-Std-006 and all other relevant international standards.

Typical Analysis															
Item	Alloy Composition(wt%)	Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
LF965-30	Sn96.5/Ag3.0/Cu0.5	Bal	2.8-3.2	0.4-0.6	0.050 Max	0.050 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF958-35	Sn95.8/Ag3.5/Cu0.7	Bal	3.3-3.7	0.6-0.8	0.050 Max	0.050 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF955-38	Sn95.5/Ag3.8/Cu0.7	Bal	3.6-4.0	0.6-0.8	0.050 Max	0.050 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
LF217	Sn95.5/Ag4.0/Cu0.5	Bal	3.8-4.2	0.4-0.6	0.050 Max	0.050 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	Sn/Ag/Cu
Melting Point, °C	217-221
Hardness, Brinell	15HB
Coefficient of Thermal Expansion	Pure Sn= 23.5
Tensile Strength, psi	4312
Density, g/cc	7.39
Electrical Resistivity , (μohm-cm)	13.0
Electrical Conductivity, %IACS	16.6

	Sn/Ag/Cu
Yield Strength, psi	3724
Total Elongation,%	27
Joint Shear Strength, at 0.1mm/min 20 C	27
Joint Shear Strength, at 0.1mm/min 100 C	17
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 20 C	13.0
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 100 C	5
Thermal Conductivity, W/m.K	58.7

### Particle Size

Sn96/Ag4 is available in Type 3(45-25um) , Type 4(38-20um) and Type 5(25-15um)J-STD-005 powder distribution. Solder powder distribution is measured utilizing laser diffraction, optical analysis and sieve analysis. Careful control of solder powder manufacturing processes ensures the particles' shape are 95% spherical minimum (aspect ratio < 1.5) and that the alloy contains a typical maximum oxide level of 80 ppm.

#### Classification of Solder Powders by Particle Size

Powder Type	Fines	Majority		Coarse		Typical Mesh
		<10%	>80%	>90%	<1%	
1	20	75-150		150	160	100/200
2	20	45-75		75	80	200/325
3	20	25-45		45	50	325/500
4	20		20-38	38	40	400/635
5	15		15-25	25	30	500
6	5		5-15	15	20	

## Metal Loading

Typical metal loading for dispensing application is **85-87%**. Compared to typical Sn63/Sn62 solder pastes manufactured with 88% by weight metal loading, DSP618D Lead Free provides as much as 10-12% higher metal volume than Sn63/Sn62. This increased in volume of DSP618D promotes better wetting and spreading of Sn/Ag/Cu Lead Free alloy.

## Solder Paste

Qualitek has developed a unique flux system designed specifically for high temperature lead free alloys. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere (normal). Since use of nitrogen is not required, DSP 618D Lead Free Solder paste will provide excellent cost savings.

In addition, DSP 618D Lead Free solder paste exhibits superior joint strength, excellent wettability, extraordinary print definition and tack life. The post soldering residues of DSP618D are non-conductive, non-corrosive and highly insulated.

### Main Features

- ❑ Excellent wetting
- ❑ Halogen-Free (Cl<900ppm, Br<900ppm, Cl+Br<1500ppm)
- ❑ Long tack time
- ❑ Low residues
- ❑ Hard non-conductive residues
- ❑ Easily dispensed

<b>Flux Classification</b>	<b>Specification</b>	<b>Test Method</b>
	ROL0	JSTD-004
<b>Copper Mirror</b>	No removal of copper film	IPC-TM-650 2.3.32
<b>Corrosion</b>	Pass	IPC-TM-650 2.6.15
<b>SIR</b>		
JSTD-004	6.55x 10 <sup>11</sup> ohms	IPC-TM-650 2.6.3.3
Bellcore (Telecordia)	5.22 x 10 <sup>11</sup> ohms	Bellcore GR-78-CORE 13.1.3
<b>Electromigration</b>	Pass	Bellcore GR-78-CORE 13.1.4
<b>Post Reflow Flux Residue</b>	45%	TGA Analysis
<b>Acid Value</b>	100-130	IPC-TM-650 2.3.13
<b>Metal Loading</b>	85.0-87.0%	IPC-TM-650 2.2.20
<b>Viscosity</b>		
Malcom <sup>(2)</sup> , Pa.S	10-150	IPC-TM-650 2.4.34.3 modified
Thixotropic Index	0.50-0.60	
<b>Slump Test</b>		
25 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
150 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
25 C, 0.33 vertical/horizontal	0.15 /0.15	IPC-TM-650 2.4.35
150 C, 0.33 vertical/horizontal	0.20/0.20	IPC-TM-650 2.4.35
<b>Solder Ball Test</b>	Pass	IPC-TM-650 2.4.43
<b>Tack</b>		
Initial	85 gm	JIS Z 3284
Tack retention @ 24 hr	110 gm	JIS Z 3284
Tack retention @ 72 hr	127 gm	JIS Z 3284

**Printing**

**Dispensing**

Needle Gauge	Needle inner diameter		Applicable powder (mesh cut)
	in.	µm	
18	0.033	838	-200+325
20	0.023	584	-325+500
21	0.020	508	-325+500
22	0.016	406	-325+500
23	0.013	330	-325+500
25	0.010	254	-400+635
27	0.008	203	-500

The clearance gap between the needle and the substrate affects the shape and quality of the dot dispensed. If the clearance is too little, the dot tends to be flattened out, and if too large, the dot tends to have long tailing.

**Pressure**

The pressure applied in the syringe should be kept at a minimum, and the proper head pressure kept in the range of 15-25 lb/in<sup>2</sup> (1.05-1.76 kg/cm<sup>2</sup>). In cases where a paste requires much higher pressure (more than 40 lb/in<sup>2</sup> or 2.82 kg/cm<sup>2</sup>) to dispense, the paste will become inconsistent and clogging may be expected. The external air pressure supply should be maintained constant.

**Open & Abandon Time**

Tests have proven that DSP618D will perform during continuous dispensing for up to 8 hrs. The paste can be left in the dispensing unit for up to 4 hours without paste drying out. If extended downtime is expected (>4 hrs) , the whole dispensing sysem should be flushed without leaving any paste in any part of the system.

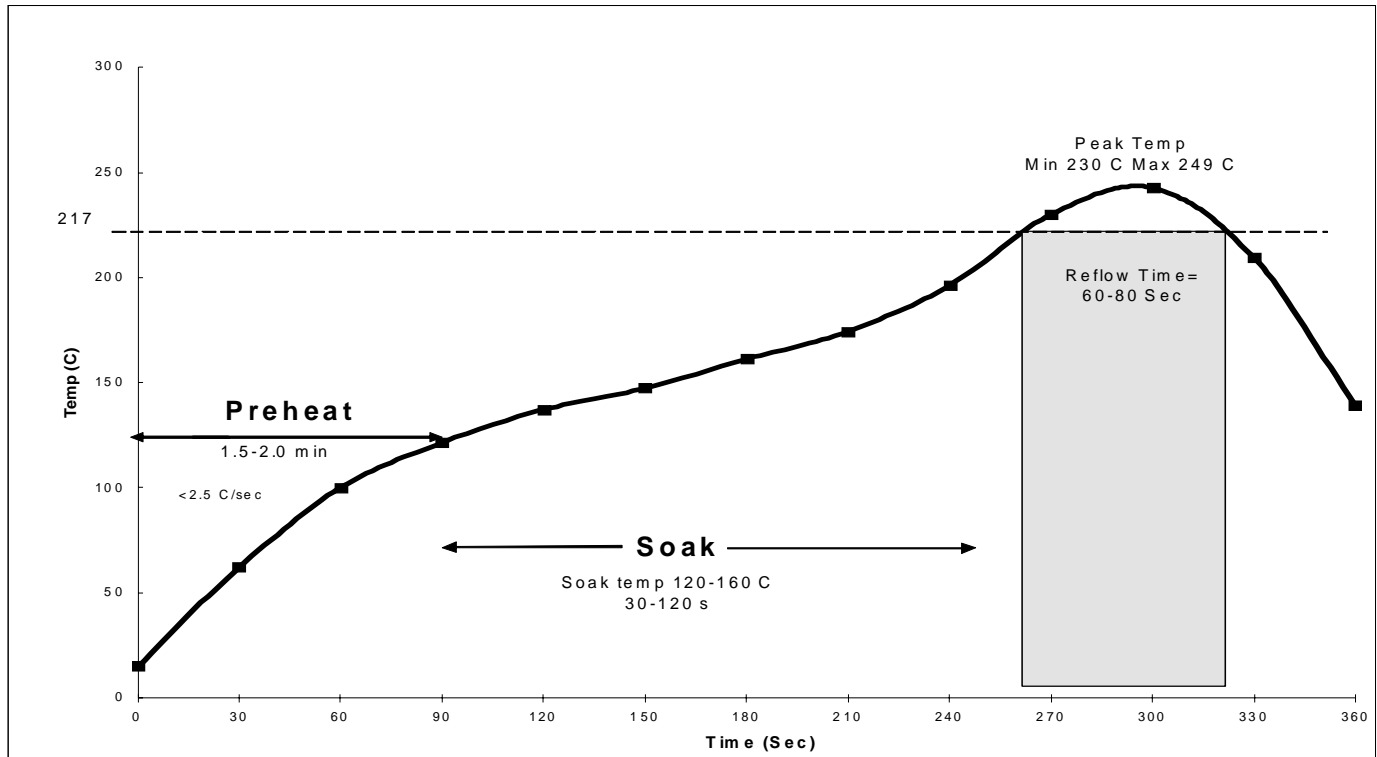
**Paste Application**

Solder paste should be taken out of the refrigerator at least 3 to 6 hours prior to use. This will give the paste enough time to come to thermal equilibrium with the environment. The flow rate of paste in a dispensing application depends on viscosity, which cn be altered by temperature change. If solder paste is supplied in syringes pre-mixing is not necessary due to the shear action produced from the dispensing.

## Reflow

Best results have been achieved when DSP 618D is reflowed in a **forced air convection** oven with a minimum of 8 zones (top&bottom), however reflow is possible with a 4 zone oven (top & bottom).

The following is a recommended profile for a forced air convection reflow process. The melting temperature of the solder, the heat resistance of the components, and the characteristics of the PCB (i.e. density, thickness, etc.) determine the actual reflow profile.



**Preheat Zone-** The preheat zone, is also referred to as the ramp zone, and is used to elevate the temperature of the PCB to the desired soak temperature. In the preheat zone the temperature of the PCB is constantly rising, at a rate that should not exceed 2.5 C/sec. The oven's preheat zone should normally occupy 25-33% of the total heated tunnel length.

**The Soak Zone-** normally occupies 33-50% of the total heated tunnel length exposes the PCB to a relatively steady temperature that will allow the components of different mass to be uniform in temperature. The soak zone also allows the flux to concentrate and the volatiles to escape from the paste.

**The Reflow Zone-** or spike zone is to elevate the temperature of the PCB assembly from the activation temperature to the recommended peak temperature. The activation temperature is always somewhat below the melting point of the alloy, while the peak temperature is always above the melting point.

## CLEANING

DSP 618D is a no clean formulation therefore the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 C (140 F) will aid in residue removal.

## **Storage & Shelf Life**

It is recommended that solder paste be stored at a temperature of between 35-50 F (2-10 C) to minimize solvent evaporation, flux separation, and chemical activity. If room temperature storage is necessary it should be maintain between 68-77F (20-25 C) .

### *Shelf life*

Unopened Container (35-50F/2-10C) 6 months (from DOM)

Unopened Container (68-77F/20-25 C) 1 months (from DOM)

Opened Container (68-77F/20-25 C) 24 hours

## **Reusing Solder Paste**

This is not normally recommended, because it typically generates more problems than it is worth. If you do decide to reuse solder paste, these pointers may be helpful. This paste should be tightly sealed and refrigerated. Then, the paste may be reused at a later date, provided that the paste has not separated or thickened significantly compared to its original properties. Storage of syringes is preferred in an upright position with tip down to prevent flux separation and air entrapment.

## **Working Environment**

Solder paste performs best when used in a controlled environment. Maintaining ambient temperature of between 68-77 F (20-25 C) at a relative humidity of 40-65% will ensure consistent performance and maximum life of paste.

## **Cleaning Misprint Boards**

If you should have a misprinted board, the paste may be cleaned off manually with alcohol (IPA) or Qualitek stencil cleaner, SK-11. If you have a more elaborate board cleaner, the paste may be easily removed with use of a 5% saponifier solution in hot DI water. Qualitek SK-44 saponifier could be used in this process.

## **Stencil Cleaning**

Periodic cleaning of the stencil during production is recommended to prevent any paste from being deposited in unwanted areas of the board. Without stencil cleaning, solder balling will increase. We recommend a periodic dry wipe (every 5 to 10 boards) with an occasional wet wipe (every 15 to 25 boards). When running fine pitch boards, the cleaning may need to become more frequent. The wet wipes should be performed with either alcohol or a stencil cleaner. Qualitek SK-11 stencil cleaner is designed for this purpose. When cleaning the stencil at the end of a job, the cleaning should be more thorough. If you have stencil cleaning equipment Qualitek SK- 44 Stencil Cleaner Saponifier is highly recommended for stencil cleaning purposes.

## **Disposal**

DSP 618D should be stored in a sealed container and disposed of in accordance with state & local authority requirements.

## **Packaging**

10cc	35 or 30 gm
30cc	100 gm
4 oz jar	250 gm